| L Numbe | r Hits | Search Text | DB | Time stamp |
|---------|--------|---|------------|-----------------|
| 1 | | (conduct\$3 near5 foil) or ((copper aluminum) | USPAT; | 2003/10/03 20:2 |
| | | near5 (film sheet)) | US-PGPUB | |
| 2 | 41998 | ((conduct\$3 near5 foil) or ((copper | USPAT; | 2003/10/03 20:2 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | |
| 3 | 29778 | | USPAT; | 2003/10/03 20:2 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | |
| | † |) and (insulat\$3 dielectric) | | |
| 4 | 19779 | | USPAT; | 2003/10/03 20:0 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | |
| | 1 |) and (insulat\$3 dielectric)) and etch\$3 | r . | |
| 5 | 17404 | ((((conduct\$3 near5 foil) or ((copper | USPAT; | 2003/10/03 20:2 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | |
| | |) and (insulat\$3 dielectric)) and etch\$3) | : | |
| _ | | and (trench recess open\$3 hole groove) | 1 | |
| ь | 16468 | ((((((conduct\$3 near5 foil) or ((copper | USPAT; | 2003/10/03 20:0 |
| | 1 | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | Í |
| | ï |) and (insulat\$3 dielectric)) and etch\$3) | 1 | |
| | | and (trench recess open\$3 hole groove)) and | | |
| 7 | 16445 | (semiconductor wafer substrate) | | |
| , | 10445 | ((((((conduct\$3 near5 foil) or ((copper | USPAT; | 2003/10/03 20:1 |
| | | aluminum) near5 (film sheet))) and pattern\$3)) and (insulat\$3 dielectric)) and etch\$3) | US-PGPUB | |
| | ! | and (insurate) dielectric// and etch53/ | : | Ĩ |
| | T | and (trench recess open\$3 hole groove)) and | i | |
| | | (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 | | |
| | | nickel))) | | |
| В | 11101 | | UODA M | 2003/10/03 20:0 |
| 0 | 11101 | aluminum) near5 (film sheet))) and pattern\$3 | USPAT; | 2003/10/03 20:0 |
| | |) and (insulat\$3 dielectric)) and etch\$3) | US-PGPUB | 1 |
| | 1 | and (trench recess open\$3 hole groove)) and | | |
| | | (semiconductor wafer substrate)) and (copper | | |
| | | Cu aluminum Al (iron?nickel (iron near3 | | 1 |
| | 1 | nickel)))) and (PR photoresist resist | ! | i |
| | į. | photo?resist) | | i |
| 9 | 5001 | ((((((((conduct\$3 near5 foil) or ((copper | USPAT: | 2003/10/03 20:2 |
| _ | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | 2003/10/03 20:2 |
| | 1 |) and (insulat\$3 dielectric)) and etch\$3) | OD FOLOR | |
| | 1 | and (trench recess open\$3 hole groove)) and | | |
| | | (semiconductor wafer substrate)) and (copper | ! | * |
| | | Cu aluminum Al (iron?nickel (iron near3 | 1 | |
| | | nickel)))) and (PR photoresist resist | | |
| | ! | photo?resist)) and resin | | |
| 10 | 147 | (((((((((conduct\$3 near5 foil) or ((copper | USPAT; | 2003/10/03 20:1 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | US-PGPUB | |
| | |) and (insulat\$3 dielectric)) and etch\$3) | | |
| | 1 | and (trench recess open\$3 hole groove)) and | | |
| | | (semiconductor wafer substrate)) and (copper | | |
| | 1 | Cu aluminum Al (iron?nickel (iron near3 | Į. | i |
| | i | nickel)))) and (PR photoresist resist | 1 | |
| | | photo?resist)) and resin) and ((electoless | | |
| | 1 | near3 plat\$3) electo?plat\$3 (electro near3 | | 1 |
| | i | plat\$3)) | | i |
| .1 | 13409 | conduct\$3 near5 foil | USPAT; | 2003/10/03 20:1 |
| | | | US-PGPUB | |
| .2 | 10122 | | USPAT; | 2003/10/03 20:1 |
| | ! | open\$3 hole groove) | US-PGPUB | |
| . 3 | 9566 | ((conduct\$3 near5 foil) and (trench recess | USPAT; | 2003/10/03 20:1 |
| | | open\$3 hole groove)) and (copper Cu aluminum | US-PGPUB | |
| | | Al (iron?nickel (iron near3 nickel))) | 1 | |
| 4 | 142 | (((conduct\$3 near5 foil) and (trench recess | USPAT; | 2003/10/03 20:1 |
| | 1 | open\$3 hole groove)) and (copper Cu aluminum | US-PGPUB | 1 |
| | Ĩ. | Al (iron?nickel (iron near3 nickel)))) and | | |
| | 1 | ((electoless near3 plat\$3) electo?plat\$3 | 1 | |
| | 1 | (electro near3 plat\$3)) | 1 | 1 |
| 5 | 6911 | conductive near3 foil | USPAT; | 2003/10/03 20:1 |
| _ | 1 | | US-PGPUB | |
| 6 | 31 | (conductive near3 foil) and (isolat\$3 near5 | USPAT; | 2003/10/03 20:1 |
| | T . | trench) | US-PGPUB | Ī |
| .7 | 65334 | (conduct\$3 near5 foil) or ((copper aluminum) | EPO; JPO; | 2003/10/03 20:2 |
| | | near5 (film sheet)) | DEDMENE. | |
| | T . | | ! DERWENT; | |

| 18 | 8676 | ((conduct\$3 near5 foil) or ((copper | EPO; JPO; | 2003/10/03 | 20:28 |
|-----|--------|---|-----------|------------|--------|
| 1 | | aluminum) near5 (film sheet))) and pattern\$3 | DERWENT; | | |
| 1 | Ĭ. | | IBM TDB | | |
| 19 | 3516 | (((conduct\$3 near5 foil) or ((copper | EPO; JPO; | 2003/10/03 | 20:28 |
| l | i | aluminum) near5 (film sheet))) and pattern\$3 | DERWENT; | | 1 |
| ĺ | |) and (insulat\$3 dielectric) | IBM_TDB | ĺ | Į. |
| 20 | , 1446 | ((((conduct\$3 near5 foil) or ((copper | EPO; JPO; | 2003/10/03 | 20:28 |
| | | aluminum) near5 (film sheet))) and pattern\$3 | DERWENT: | i i | 1 |
| ! | 1 |) and (insulat\$3 dielectric)) and (trench | IBM TDB | L | |
| | | recess open\$3 hole groove) | _ | | |
| 21 | 271 | (((((conduct\$3 near5 foil) or ((copper | EPO; JPO; | 2003/10/03 | 20:29. |
| | | aluminum) near5 (film sheet))) and pattern\$3 | DERWENT: | | l l |
| | |) and (insulat\$3 dielectric)) and (trench | IBM TDB | ļ | |
| | | recess open\$3 hole groove)) and resin | 12 | | |
| : - | | recess opens note groover, and restin | | | |

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